

NICOLAS REED

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EDUCATION

University of California, Berkeley <i>B.S. Electrical Engineering & Computer Sciences (EECS)</i>	GPA: 3.68/4.00 Expected May 2027
Relevant coursework: Tapeout, Digital Design and Integrated Circuits (with ASIC Lab), Computer Architecture, Operating Systems, Signals and Circuits, Data Structures, Internet of Things, Foundations of Data Science	

EXPERIENCE

Apple <i>[Incoming] Hardware Engineering Intern</i>	Cupertino, CA May 2026 – August 2026
• Silicon Engineering Group: SoC Design Verification	
Sandisk <i>Software Development Intern</i>	Milpitas, CA May 2025 – August 2025
• Reconciled CMDB and inventory data for 40,000+ virtual machines with Pandas, standardizing records, surfacing gaps, and producing migration plans for a cloud provider transition.	
• Built an AI assistant with LlamaIndex and NLP to streamline license and contract workflows across 10,000 enterprise applications, improving compliance and reducing spend.	
UC Berkeley SLICE Lab <i>Undergraduate Research Assistant - advised by Professor Sagar Karandikar</i>	Berkeley, CA May 2025 – Present
• Created a telemetry pipeline for Chipyard and FireSim on AWS S3, boosting debugging and reproducibility.	
• Prepared a structured dataset of runs and metrics to enable LLM-driven regression triage and automated insights.	
UC Berkeley Electrical Engineering & Computer Sciences (EECS) <i>Head Teaching Assistant</i>	Berkeley, CA June 2024 – Present
• Support 1,200+ students with C, RISC-V, and Python through office hours and an online forum.	
• Ranked 1st among staff in helpfulness and teaching effectiveness.	
• Host weekly lab sections for 50+ students, guiding programming exercises and problem-solving practice.	
• Develop weekly homework and lab assignments, and maintain course infrastructure using GitHub and Docker.	
• Answer 1,500+ student questions per semester to lead online forum engagement.	
Micross Components - Silicon Turnkey Solutions <i>Engineering Intern</i>	Milpitas, CA July 2023 – August 2023
• Conducted mechanical and PCB testing on 1,000+ devices, translating results into actionable insights via Excel.	
• Resolved a test issue by documenting compromised semiconductors and identifying the damage stage.	

PROJECTS

TSMC 16nm IoT SoC Tapeout - Chisel, Chipyard, Hammer	2026
• Contributed to a large-scale SoC tapeout with Apple mentorship, owning a block and driving signoff closure.	
5-Stage Pipelined RISC-V CPU with I/D Caches - Verilog	2025
• Apple New Silicon Initiative Design Contest Winner: delivered best performance and area.	
• Boosted throughput and frequency by refining hazard control and forwarding, reducing stall cycles.	
• Achieved single-cycle read hits and two-cycle write hits and implemented optimized write-back logic.	
Pintos Operating System - C	2025
• Extended core OS support for process control and system calls, handling invalid user memory safely.	
• Added multithreading and synchronization primitives, enforcing priority scheduling to prevent inversion.	
• Built UNIX-style file system features including caching, file growth, and subdirectories to improve I/O.	
Scheme Interpreter - Python	2024
• Implemented an interpreter for a subset of Lisp (Scheme), supporting core expressions and syntax.	
• Applied semantic and lexical analysis techniques that machines use to evaluate and execute code.	

TECHNICAL SKILLS

Languages: Verilog, SystemVerilog, C, Python, RISC-V, Chisel, Scala, Java, x86. SQL, MATLAB
Tools & Frameworks: Git, Cadence Innovus, GDB, Valgrind, Pandas, NumPy, Docker, LTSpice